74AUP1G34-Q100

Low-power buffer Rev. 1 — 26 March 2013

Product data sheet

General description 1.

The 74AUP1G34-Q100 provides a low-power, low-voltage single buffer.

Schmitt trigger action at all inputs makes the circuit tolerant to slower input rise and fall times across the entire V_{CC} range from 0.8 V to 3.6 V.

This device ensures a very low static and dynamic power consumption across the entire V_{CC} range from 0.8 V to 3.6 V.

This device is fully specified for partial power-down applications using I_{OFF}.

The I_{OFF} circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

Features and benefits 2.

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - ◆ Specified from -40 °C to +85 °C and from -40 °C to +125 °C
- Wide supply voltage range from 0.8 V to 3.6 V
- High noise immunity
- Complies with JEDEC standards:
 - ◆ JESD8-12 (0.8 V to 1.3 V)
 - ◆ JESD8-11 (0.9 V to 1.65 V)
 - ◆ JESD8-7 (1.2 V to 1.95 V)
 - JESD8-5 (1.8 V to 2.7 V)
 - ◆ JESD8-B (2.7 V to 3.6 V)
- ESD protection:
 - ♦ MIL-STD-883, method 3015 Class 3A. Exceeds 5000 V
 - ◆ HBM JESD22-A114F Class 3A. Exceeds 5000 V
 - ♦ MM JESD22-A115-A exceeds 200 V (C = 200 pF, R = 0 Ω)
- Low static power consumption; I_{CC} = 0.9 μA (maximum)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Inputs accept voltages up to 3.6 V
- Low noise overshoot and undershoot < 10 % of V_{CC}
- I_{OFF} circuitry provides partial power-down mode operation
- Multiple package options



3. Ordering information

Table 1. Ordering information

Type number	Package										
	Temperature range	Name	Description	Version							
74AUP1G34GW-Q100	-40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1							

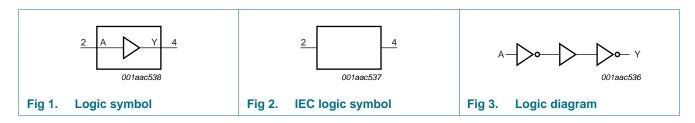
4. Marking

Table 2. Marking

Type number	Marking code ^[1]
74AUP1G34GW-Q100	aN

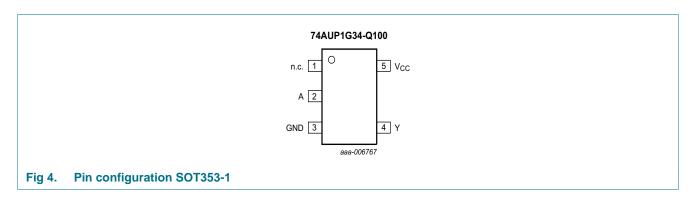
[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram



6. Pinning information

6.1 Pinning



6.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
n.c.	1	not connected
A	2	data input
GND	3	ground (0 V)
Υ	4	data output
V _{CC}	5	supply voltage

7. Functional description

Table 4. Function table[1]

Input	Output
Α	Υ
L	L
Н	Н

^[1] H = HIGH voltage level;L = LOW voltage level.

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+4.6	V
I _{IK}	input clamping current	V _I < 0 V	-50	-	mA
VI	input voltage		[<u>1</u>] -0.5	+4.6	V
I _{OK}	output clamping current	V _O < 0 V	-50	-	mA
Vo	output voltage	Active mode and Power-down mode	[<u>1</u>] -0.5	+4.6	V
Io	output current	$V_O = 0 V \text{ to } V_{CC}$	-	±20	mA
I _{CC}	supply current		-	+50	mA
I_{GND}	ground current		-50	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	$T_{amb} = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}$	[2] _	250	mW

^[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^[2] For TSSOP5 packages: above 87.5 °C the value of Ptot derates linearly with 4.0 mW/K.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		0.8	3.6	V
VI	input voltage		0	3.6	V
Vo	output voltage	Active mode	0	V_{CC}	V
		Power-down mode; V _{CC} = 0 V	0	3.6	V
T _{amb}	ambient temperature		-40	+125	°C
Δt/ΔV	input transition rise and fall rate	$V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	0	200	ns/V

10. Static characteristics

Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ Max	Unit
T _{amb} = 2	5 °C				
V _{IH}	HIGH-level input voltage	$V_{CC} = 0.8 \text{ V}$	$0.70 \times V_{CC}$		V
		V _{CC} = 0.9 V to 1.95 V	$0.65 \times V_{CC}$		V
		V_{CC} = 2.3 V to 2.7 V	1.6		V
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	2.0		V
V_{IL}	LOW-level input voltage	$V_{CC} = 0.8 \text{ V}$	-	- 0.30 × V	cc V
		V _{CC} = 0.9 V to 1.95 V	-	- 0.35 × V	cc V
		V_{CC} = 2.3 V to 2.7 V	-	- 0.7	V
		V _{CC} = 3.0 V to 3.6 V	-	- 0.9	V
V _{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}			
		$I_{O} = -20 \mu A$; $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	$V_{CC}-0.1$		V
		$I_O = -1.1 \text{ mA}; V_{CC} = 1.1 \text{ V}$	$0.75 \times V_{CC}$		V
		$I_{O} = -1.7 \text{ mA}; V_{CC} = 1.4 \text{ V}$	1.11		V
		$I_{O} = -1.9 \text{ mA}; V_{CC} = 1.65 \text{ V}$	1.32		V
		$I_{O} = -2.3 \text{ mA}; V_{CC} = 2.3 \text{ V}$	2.05		V
		$I_{O} = -3.1 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.9		V
		$I_{O} = -2.7 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.72		V
		$I_{O} = -4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.6		V
V _{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}			
		$I_O = 20 \mu A$; $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	- 0.1	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	- 0.3 × V _C	c V
		$I_{O} = 1.7 \text{ mA}; V_{CC} = 1.4 \text{ V}$	-	- 0.31	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	- 0.31	V
		$I_{O} = 2.3 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	- 0.31	V
		$I_O = 3.1 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	- 0.44	V
		$I_{O} = 2.7 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	- 0.31	V
		I_{O} = 4.0 mA; V_{CC} = 3.0 V	-	- 0.44	V
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 Table 7.
 Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
l _l	input leakage current	V_I = GND to 3.6 V; V_{CC} = 0 V to 3.6 V	-	-	±0.1	μΑ
OFF	power-off leakage current	V_I or V_O = 0 V to 3.6 V; V_{CC} = 0 V	-	-	±0.2	μΑ
ΔI_{OFF}	additional power-off leakage current	V_1 or $V_0 = 0$ V to 3.6 V; $V_{CC} = 0$ V to 0.2 V	-	-	±0.2	μΑ
CC	supply current	V_I = GND or V_{CC} ; I_O = 0 A; V_{CC} = 0.8 V to 3.6 V	-	-	0.5	μΑ
Δl _{CC}	additional supply current	$V_1 = V_{CC} - 0.6 \text{ V}; I_O = 0 \text{ A};$ $V_{CC} = 3.3 \text{ V}$	[1] -	-	40	μΑ
Cı	input capacitance	V_{CC} = 0 V to 3.6 V; V_I = GND or V_{CC}	-	0.8	-	рF
Co	output capacitance	$V_O = GND; V_{CC} = 0 V$	-	1.7	-	рF
T _{amb} = -	40 °C to +85 °C					
V _{IH}	HIGH-level input voltage	V _{CC} = 0.8 V	$0.70 \times V_{CC}$	-	-	V
		V _{CC} = 0.9 V to 1.95 V	$0.65 \times V_{CC}$	-	-	V
		V _{CC} = 2.3 V to 2.7 V	1.6	-	-	V
		V _{CC} = 3.0 V to 3.6 V	2.0	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 0.8 V	-	-	$0.30 \times V_{CC}$	V
		V _{CC} = 0.9 V to 1.95 V	-	-	$0.35 \times V_{CC}$	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V _{CC} = 3.0 V to 3.6 V	-	-	0.9	V
V _{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		$I_{O} = -20 \mu A$; $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	V _{CC} - 0.1	-	-	V
		$I_{O} = -1.1 \text{ mA}; V_{CC} = 1.1 \text{ V}$	$0.7 \times V_{CC}$	-	-	٧
		$I_{O} = -1.7 \text{ mA}; V_{CC} = 1.4 \text{ V}$	1.03	-	-	٧
		$I_{O} = -1.9 \text{ mA}; V_{CC} = 1.65 \text{ V}$	1.30	-	-	V
		$I_{O} = -2.3 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.97	-	-	V
		$I_{O} = -3.1 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.85	-	-	V
		$I_{O} = -2.7 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.67	-	-	V
		$I_{O} = -4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.55	-	-	V
V _{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		$I_O = 20 \mu A$; $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	0.1	V
		$I_O = 1.1 \text{ mA}; V_{CC} = 1.1 \text{ V}$	-	-	$0.3 \times V_{CC}$	V
		$I_O = 1.7 \text{ mA}; V_{CC} = 1.4 \text{ V}$	-	-	0.37	V
		$I_O = 1.9 \text{ mA}; V_{CC} = 1.65 \text{ V}$	-	-	0.35	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.33	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.45	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.33	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.45	V
 	input leakage current	V _I = GND to 3.6 V; V _{CC} = 0 V to 3.6 V	-	-	±0.5	μΑ
l _{OFF}	power-off leakage current	V_1 or $V_0 = 0$ V to 3.6 V; $V_{CC} = 0$ V	-	-	±0.5	μΑ
Δl_{OFF}	additional power-off	$V_1 \text{ or } V_0 = 0 \text{ V to } 3.6 \text{ V};$ $V_{CC} = 0 \text{ V to } 0.2 \text{ V}$	-	-	±0.6	μΑ

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 Table 7.
 Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
I _{CC}	supply current	V_I = GND or V_{CC} ; I_O = 0 A; V_{CC} = 0.8 V to 3.6 V		-	-	0.9	μΑ
Δl _{CC}	additional supply current	$V_{I} = V_{CC} - 0.6 \text{ V}; I_{O} = 0 \text{ A};$ $V_{CC} = 3.3 \text{ V}$	<u>[1]</u>	-	-	50	μΑ
T _{amb} = -	40 °C to +125 °C						
V_{IH}	HIGH-level input voltage	V _{CC} = 0.8 V		$0.75 \times V_{CC}$	-	-	V
		V _{CC} = 0.9 V to 1.95 V		$0.70 \times V_{CC}$	-	-	V
		V _{CC} = 2.3 V to 2.7 V		1.6	-	-	V
		V _{CC} = 3.0 V to 3.6 V		2.0	-	-	V
V_{IL}	LOW-level input voltage	V _{CC} = 0.8 V		-	-	$0.25 \times V_{CC}$	V
		V _{CC} = 0.9 V to 1.95 V		-	-	$0.30 \times V_{CC}$	V
		V _{CC} = 2.3 V to 2.7 V		-	-	0.7	V
		V _{CC} = 3.0 V to 3.6 V		-	-	0.9	V
V _{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}					
		$I_O = -20 \mu A$; $V_{CC} = 0.8 \text{ V}$ to 3.6 V		V _{CC} - 0.11	-	-	V
		$I_O = -1.1 \text{ mA}; V_{CC} = 1.1 \text{ V}$		$0.6 \times V_{CC}$	-	-	V
		$I_{O} = -1.7 \text{ mA}; V_{CC} = 1.4 \text{ V}$		0.93	-	-	V
		$I_{O} = -1.9 \text{ mA}; V_{CC} = 1.65 \text{ V}$		1.17	-	-	V
		$I_{O} = -2.3 \text{ mA}; V_{CC} = 2.3 \text{ V}$		1.77	-	-	V
		$I_{O} = -3.1 \text{ mA}; V_{CC} = 2.3 \text{ V}$		1.67	-	-	V
		$I_{O} = -2.7 \text{ mA}; V_{CC} = 3.0 \text{ V}$		2.40	-	-	V
		$I_{O} = -4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$		2.30	-	-	V
V _{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}					
		$I_O = 20 \mu A$; $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$		-	-	0.11	V
		$I_O = 1.1 \text{ mA}; V_{CC} = 1.1 \text{ V}$		-	-	$0.33 \times V_{CC}$	V
		$I_O = 1.7 \text{ mA}; V_{CC} = 1.4 \text{ V}$		-	-	0.41	V
		$I_O = 1.9 \text{ mA}; V_{CC} = 1.65 \text{ V}$		-	-	0.39	V
		$I_O = 2.3 \text{ mA}; V_{CC} = 2.3 \text{ V}$		-	-	0.36	V
		$I_O = 3.1 \text{ mA}; V_{CC} = 2.3 \text{ V}$		-	-	0.50	V
		$I_{O} = 2.7 \text{ mA}; V_{CC} = 3.0 \text{ V}$		-	-	0.36	V
		$I_O = 4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$		-	-	0.50	V
l _l	input leakage current	$V_I = GND$ to 3.6 V; $V_{CC} = 0$ V to 3.6 V		-	-	±0.75	μΑ
I _{OFF}	power-off leakage current	V_I or $V_O = 0$ V to 3.6 V; $V_{CC} = 0$ V		-	-	±0.75	μΑ
ΔI_{OFF}	additional power-off leakage current	V_1 or $V_0 = 0$ V to 3.6 V; $V_{CC} = 0$ V to 0.2 V		-	-	±0.75	μΑ
I _{CC}	supply current	V_I = GND or V_{CC} ; I_O = 0 A; V_{CC} = 0.8 V to 3.6 V		-	-	1.4	μΑ
Δl _{CC}	additional supply current	$V_I = V_{CC} - 0.6 \text{ V}; I_O = 0 \text{ A};$ $V_{CC} = 3.3 \text{ V}$	<u>[1]</u>	-	-	75	μΑ

^[1] One input at V_{CC} – 0.6 V, other input at V_{CC} or GND.

11. Dynamic characteristics

Table 8. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see Figure 6.

Symbol	Parameter	Conditions		Tar	_{nb} = 25	°C	Taı	_{nb} = -40 °	°C to +	125 °C	Unit	
				Min	Typ[1]	Max	Min	Max (85 °C)	Min	Max (125 °C)		
$C_L = 5 p$	F	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \								1		
t _{pd}	propagation	A to Y; see Figure 5	[2]									
	delay	V _{CC} = 0.8 V		-	15.0	-	-	-	-	-	ns	
		$V_{CC} = 1.1 \text{ V to } 1.3 \text{ V}$		2.6	4.7	9.2	2.0	10.0	2.0	11.0	ns	
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		2.1	3.4	5.7	1.6	6.5	1.6	7.2	ns	
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		1.8	2.9	4.5	1.4	5.2	1.4	5.8	ns	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		1.5	2.3	3.5	1.2	4.2	1.2	4.6	ns	
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$		1.4	2.1	3.2	1.0	3.8	1.0	4.2	ns	
C _L = 10	pF											
t _{pd}	propagation	A to Y; see Figure 5	[2]									
	delay	V _{CC} = 0.8 V		-	18.4	-	-	-	-	-	ns	
		$V_{CC} = 1.1 \text{ V to } 1.3 \text{ V}$		3.2	5.6	10.9	2.3	11.8	2.3	13.1	ns	
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		2.6	4.1	6.7	1.9	7.7	1.9	8.5	ns	
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		2.3	3.4	5.3	1.7	6.2	1.7	6.9	ns	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2.0	2.9	4.2	1.5	5.0	1.5	5.5	ns	
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$		1.7	2.6	3.8	1.4	4.6	1.4	5.1	ns	
C _L = 15	pF											
t_{pd}	propagation	A to Y; see Figure 5	[2]									
	delay	$V_{CC} = 0.8 \text{ V}$		-	21.9	-	-	-	-	-	ns	
		$V_{CC} = 1.1 \text{ V to } 1.3 \text{ V}$		3.6	6.4	12.6	2.6	13.8	2.6	15.2	ns	
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		3.0	4.6	7.6	2.2	8.9	2.2	9.8	ns	
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		2.6	3.9	6.0	2.0	7.2	2.0	7.9	ns	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2.3	3.3	4.8	1.8	5.7	1.8	6.3	ns	
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$		2.1	3.1	4.2	1.6	5.0	1.6	5.5	ns	
C _L = 30	pF											
t _{pd}	propagation	A to Y; see Figure 5	[2]									
	delay	$V_{CC} = 0.8 \text{ V}$		-	32.1	-	-	-	-	-	ns	
		$V_{CC} = 1.1 \text{ V to } 1.3 \text{ V}$		4.8	8.7	16.3	3.6	18.9	3.6	20.8	ns	
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		4.0	6.2	10.3	3.4	12.2	3.4	13.4	ns	
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		3.6	5.2	8.1	3.2	9.8	3.2	10.8	ns	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		3.0	4.4	6.4	2.7	7.7	2.7	8.5	ns	
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$		2.9	4.2	5.6	2.5	6.5	2.5	7.2	ns	

 Table 8.
 Dynamic characteristics ...continued

Voltages are referenced to GND (ground = 0 V); for test circuit see Figure 6.

Symbol	Parameter	Conditions		T _{amb} = 25 °C		$T_{amb} = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}$				Unit	
				Min	Typ[1]	Max	Min	Max (85 °C)	Min	Max (125 °C)	
C_{PD}	power dissipation	$f_i = 1 \text{ MHz};$ $V_I = \text{GND to } V_{CC}$	[3]		'	•					
	capacitance	$V_{CC} = 0.8 \text{ V}$		-	2.5	-	-	-	-	-	pF
		$V_{CC} = 1.1 \text{ V to } 1.3 \text{ V}$		-	2.6	-	-	-	-	-	pF
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		-	2.7	-	-	-	-	-	pF
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		-	2.9	-	-	-	-	-	pF
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-	3.4	-	-	-	-	-	pF
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$		-	4.0	-	-	-	-	-	pF

- [1] All typical values are measured at nominal V_{CC} .
- [2] t_{pd} is the same as t_{PLH} and t_{PHL} .
- [3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma (C_L \times V_{CC}^2 \times f_o)$ where:

 f_i = input frequency in MHz;

 f_o = output frequency in MHz;

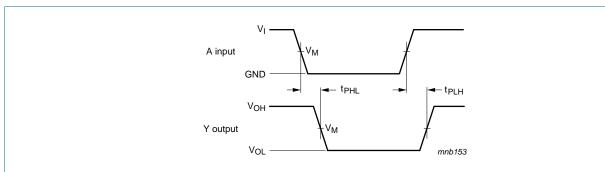
C_L = output load capacitance in pF;

 V_{CC} = supply voltage in V;

N = number of inputs switching;

 $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

12. Waveforms



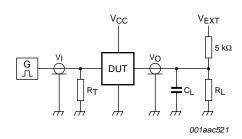
Measurement points are given in Table 9.

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 5. The data input (A) to output (Y) propagation delays

Table 9. Measurement points

Supply voltage	Output	Input						
V _{CC}	V _M	V _M	V _I	$t_r = t_f$				
0.8 V to 3.6 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V _{CC}	≤ 3.0 ns				



Test data is given in Table 10.

Definitions for test circuit:

 R_L = Load resistance.

 C_L = Load capacitance including jig and probe capacitance.

 R_T = Termination resistance should be equal to the output impedance Z_0 of the pulse generator.

 V_{EXT} = External voltage for measuring switching times.

Fig 6. Test circuit for measuring switching times

Table 10. Test data

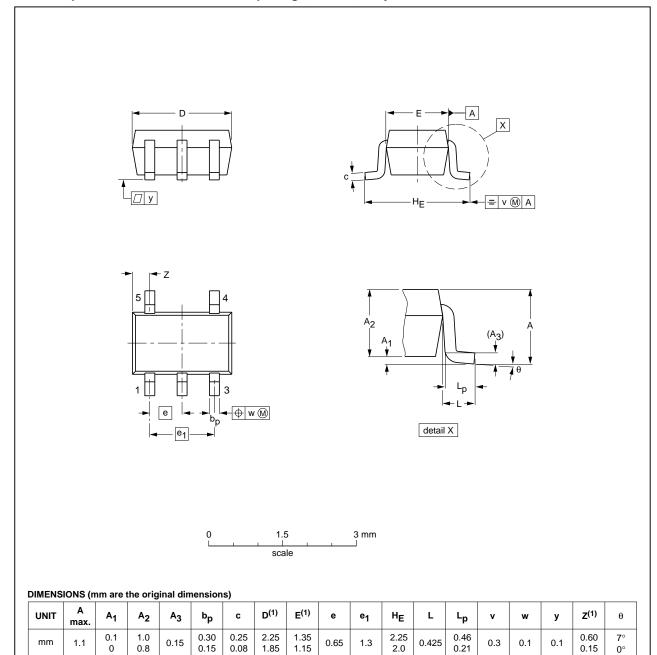
Supply voltage	Load		V _{EXT}		
V _{CC}	C _L	R _L [1]	t _{PLH} , t _{PHL}	t _{PZH} , t _{PHZ}	t _{PZL} , t _{PLZ}
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 k Ω or 1 M Ω	open	GND	$2\times V_{CC}$

[1] For measuring enable and disable times, R_L = 5 k Ω . For measuring propagation delays, setup and hold times and pulse width, R_L = 1 M Ω .

13. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1



1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

	OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
;	SOT353-1		MO-203	SC-88A			-00-09-01 03-02-19

Fig 7. Package outline SOT353-1 (TSSOP5)

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14. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
НВМ	Human Body Model
MIL	Military
MM	Machine Model

15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AUP1G34_Q100 v.1	20130326	Product data sheet	-	-

16. Legal information

16.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
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